

Product Change Notification - KMIO-24FXKZ027

Date: 10 Nov 2017
Product Category: Capacitive Touch Sensors; Temperature Sensors; Current And Power Measurement ICs
Notification subject: CCB 2719 Final Notice: Qualification of G700Y mold compound for selected product available on 10L VDFN package at ANAP assembly site.
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of G700Y mold compound for selected product available on 10L VDFN package at ANAP assembly site.

Pre Change:
Assembled using GE7470LA mold compound.

Post Change:
Assembled using G700Y mold compound.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Technology Philippine INC.(ANAP)	Amkor Technology Philippine INC.(ANAP)
Wire material	Au wire	Au wire
Die attach material	AMK-06	AMK06
Molding compound material	GE7470LA	G700Y
Lead frame material	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To Improve on-time delivery performance by qualifying G700Y mold compound at ANAP assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:

December 10, 2017 (date code: 1750)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2016				->	November 2017				December 2017				
	31	32	33	34		44	45	46	47	48	49	50	51	52
Initial PCN Issue Date				X										
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date											X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:**August 24, 2016:** Issued initial notification.**November 10, 2017:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date on December 10, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):[PCN_KMIO-24FXKZ027_Affected CPN.pdf](#)[PCN_KMIO-24FXKZ027_Qual Report.pdf](#)[PCN_KMIO-24FXKZ027_Affected CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_KMIO-24FXKZ027
CATALOG_PART_NBR
CAP1006-1-AIA-TR
CAP1106-1-AIA-TR
CAP1133-1-AIA-TR
EMC1403-1-AIA-TR
EMC1403-2-AIA-TR
EMC1413-A-AIA-TR
EMC1414-A-AIA-TR
EMC1444-A-AIA-TR
EMC1464-A-AIA-TR
EMC1183-A-AIA-TR
EMC1184-A-AIA-TR
EMC1187-1-AIA-TR
EMC1188-1-AIA-TR
CAP1206-1-AIA
CAP1296-1-AIA
CAP1206-1-AIA-TR
CAP1206-2-AIA-TR
CAP1296-1-AIA-TR
CAP1296-2-AIA-TR
PAC1710-1-AIA-TR
PAC1720-1-AIA-TR
PAC1921-1-AIA-TR